



SOT429

plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3 lead TO-247

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-247
Package type industry code	TO-247
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-247
Mounting method type	H (heatsink mount)
Issue date	25-3-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		20.3	-	20.45	20.6	mm
E	package width		15.45	-	15.6	15.75	mm
A	seated height		4.7	-	4.95	5.2	mm
e	nominal pitch		-	-	5.45	-	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

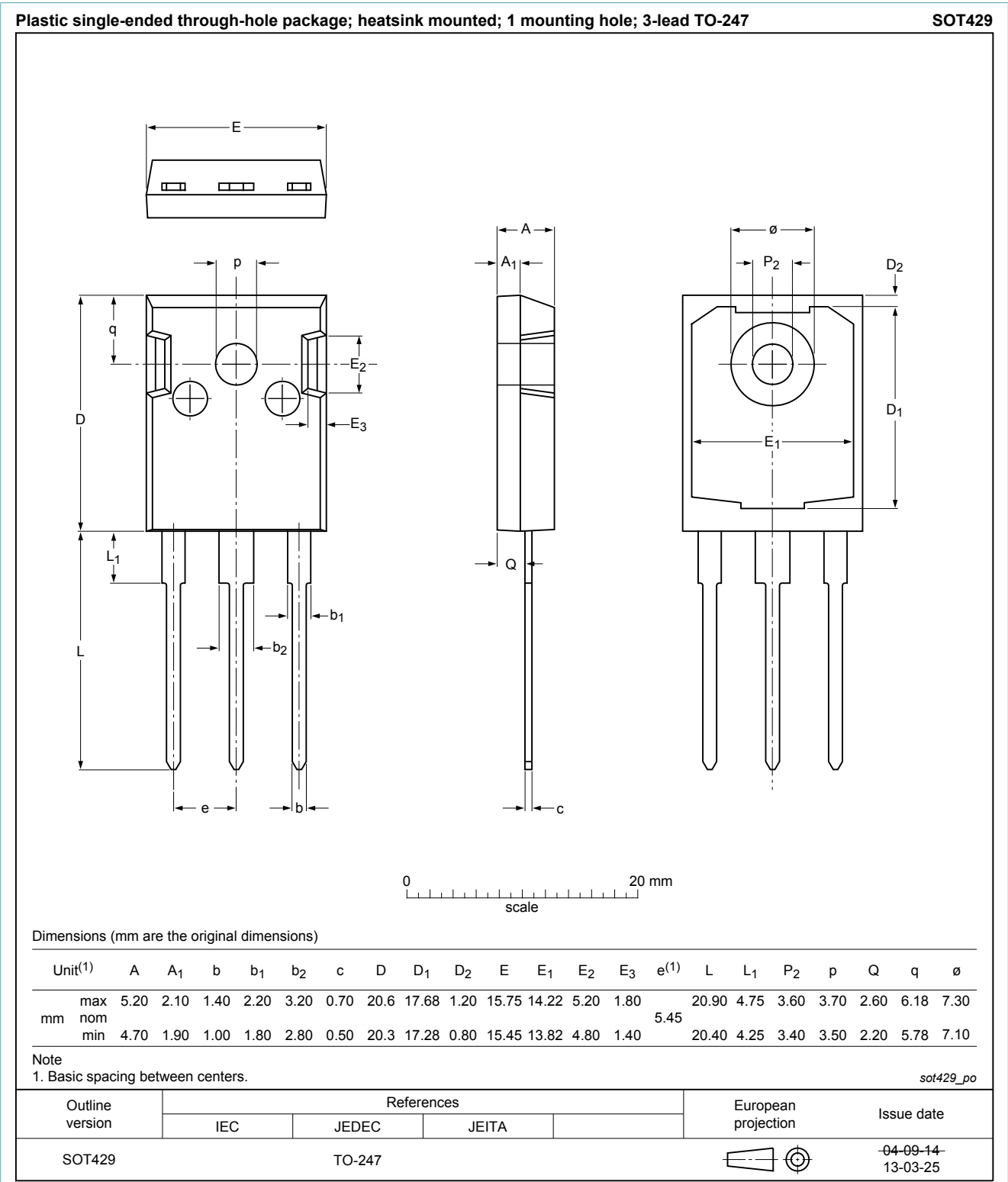


Fig. 1. Package outline TO-247 (SOT429)

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3. Legal information

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